



Material Content Data Sheet



Sales Product Name				IAUC60N04S6L039		Issued		12. August 2019	
MA#				MA001701320					
Package				PG-TDSON-8-33		Weight*		111.32 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.373	0.34	0.34	3355	3355	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		143		
	non noble metal	iron	7439-89-6	0.053	0.05		475		
wire	non noble metal	copper	7440-50-8	52.842	47.46	47.52	474677	475295	
	noble metal	gold	7440-57-5	0.044	0.04	0.04	400	400	
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		692		
	plastics	epoxy resin	-	6.085	5.47		54665		
leadfinish	inorganic material	silicondioxide	60676-86-0	32.353	29.06	34.60	290627	345984	
	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14137	14137	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1879	1879	
solder	non noble metal	tin	7440-31-5	0.011	0.01		96		
	noble metal	silver	7440-22-4	0.013	0.01		120		
heat sink clip	non noble metal	lead	7439-92-1	0.511	0.46	0.48	4591	4807	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
heatspreader	non noble metal	iron	7439-89-6	0.017	0.02		151		
	non noble metal	copper	7440-50-8	16.828	15.12	15.14	151162	151358	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
*deviation	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2781	2785	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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